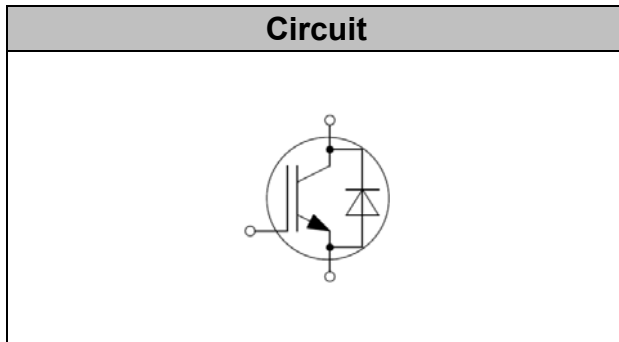




IGBT Discrete

V_{CE}	650	V
I_C	40	A
$V_{CE(SAT)} I_C=40A$	1.95	V



Applications

- High frequency switching application
- Medical applications
- Uninterruptible power supply
- Motion/servo control

Features

- Low switching losses
- Maximum junction temperature 175°C
- Positive temperature coefficient
- High ruggedness, temperature stable
- High short circuit capability(5us)

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emitter Breakdown Voltage	V_{CE}	650	V
DC Collector Current, limited by T_{jmax} $T_C=25^\circ C$ $T_C=100^\circ C$	I_C	80 40	A
Diode Forward Current, limited by T_{jmax} $T_C=25^\circ C$ $T_C=100^\circ C$	I_F	80 40	A
Continuous Gate-Emitter Voltage	V_{GE}	± 20	V
Transient Gate-Emitter Voltage	V_{GE}	± 30	V
Turn off Safe Operating Area $V_{CE} \leq 1200V$, $T_j \leq 150^\circ C$		160	A
Pulsed Collector Current, $V_{GE}=15V$, t_p limited by T_{jmax}	I_{CM}	160	A
Diode Pulsed Current, t_p limited by T_{jmax}	I_{Fpuls}	120	A
Short Circuit Withstand Time, $V_{GE}=15V$, $V_{CC}=400V$, $V_{CEM} \leq 650V$	T_{sc}	5	μs
Power Dissipation, $T_j=175^\circ C$, $T_c=25^\circ C$	P_{tot}	306	W



Operating Junction Temperature	T_j	-40...+175	°C
Storage Temperature	T_s	-55...+150	°C
Soldering Temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	°C

Electrical Characteristics of the IGBT ($T_j = 25^\circ\text{C}$ unless otherwise specified):

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Collector-Emitter Breakdown Voltage	BV_{CES}	$V_{GE}=0V, I_C=250\mu A$	650		-	V
Gate Threshold Voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=0.6mA$	4.5	5.0	5.5	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=40A$ $T_j=25^\circ\text{C}$, $T_j=125^\circ\text{C}$ $T_j=150^\circ\text{C}$		1.95 2.30 2.40	2.40	V
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE}=650V, V_{GE}=0V$ $T_j=25^\circ\text{C}$, $T_j=150^\circ\text{C}$			0.25 4.00	mA
Gate-Emitter Leakage Current	I_{GES}	$V_{CE}=0V, V_{GE}=\pm 20V$			100	nA

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic						
Input Capacitance	C_{ies}	$V_{CE}=25V, V_{GE}=0V,$ $f=1MHz$	-	1.56	-	nF
Reverse Transfer Capacitance	C_{res}		-	0.06	-	
Gate Charge	Q_G	$V_{CC}=300V, I_C=30A,$ $V_{GE}=15V$	-	0.16	-	uC
Short Circuit Collector Current	I_{SC}	$V_{GE}=15V, t_{sc}\leq 5\mu s,$ $V_{CC}=300V, T_j\leq 150^\circ\text{C}$	-	200	-	A



Electrical Characteristics of the Diode (T_j= 25°C unless otherwise specified):

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Diode Forward Voltage	V _F	I _F = 40A T _j = 25°C, T _j = 125°C T _j = 150°C		1.70 1.65 1.65	2.50	V

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic , at T_j= 25°C						
Turn-on Delay Time	t _{d(on)}	V _{CC} =300V, I _C =40A, V _{GE} = -15V~15V, R _g =20Ω, L _s =60nH	-	30	-	ns
Rise Time	t _r		-	64	-	ns
Turn-on Energy	E _{on}		-	1.35	-	mJ
Turn-off Delay Time	t _{d(off)}		-	93	-	ns
Fall Time	t _f		-	58	-	ns
Turn-off Energy	E _{off}		-	0.43	-	mJ
Dynamic , at T_j= 125°C						
Turn-on Delay Time	t _{d(on)}	V _{CC} =300V, I _C =40A,, V _{GE} = -15V~15V, R _g =20Ω, L _s =60nH	-	45	-	ns
Rise Time	t _r		-	72	-	ns
Turn-on Energy	E _{on}		-	1.80	-	mJ
Turn-off Delay Time	t _{d(off)}		-	160	-	ns
Fall Time	t _f		-	65	-	ns
Turn-off Energy	E _{off}		-	0.65	-	mJ
Dynamic , at T_j= 150°C						
Turn-on Delay Time	t _{d(on)}	V _{CC} =300V, I _C =40A,, V _{GE} = -15V~15V, R _g =20Ω, L _s =60nH	-	48	-	ns
Rise Time	t _r		-	74	-	ns
Turn-on Energy	E _{on}		-	1.97	-	mJ
Turn-off Delay Time	t _{d(off)}		-	165	-	ns
Fall Time	t _f		-	68	-	ns
Turn-off Energy	E _{off}		-	0.74	-	mJ

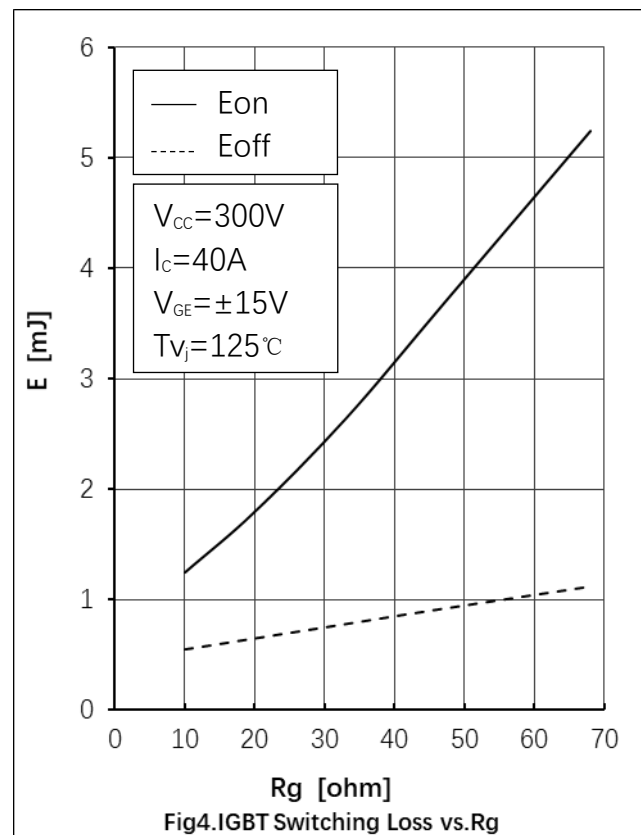
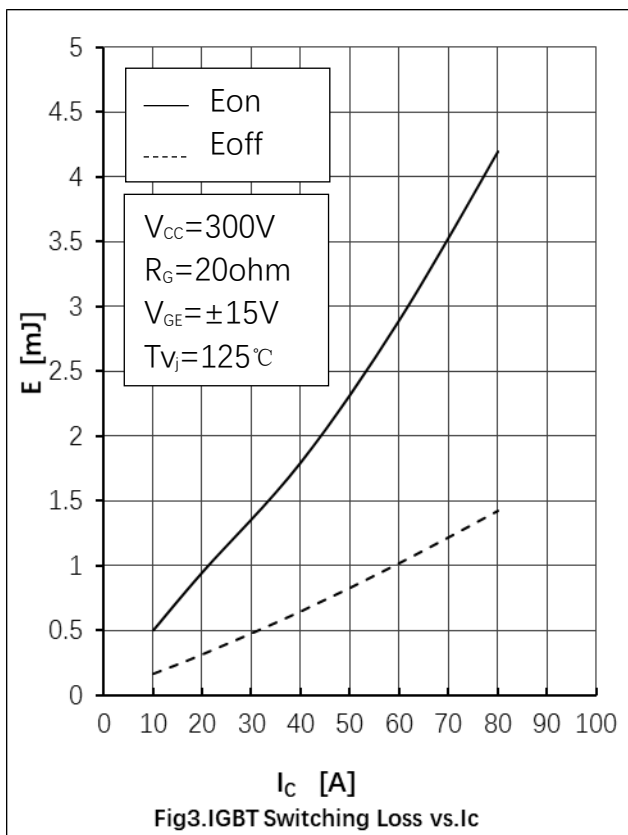
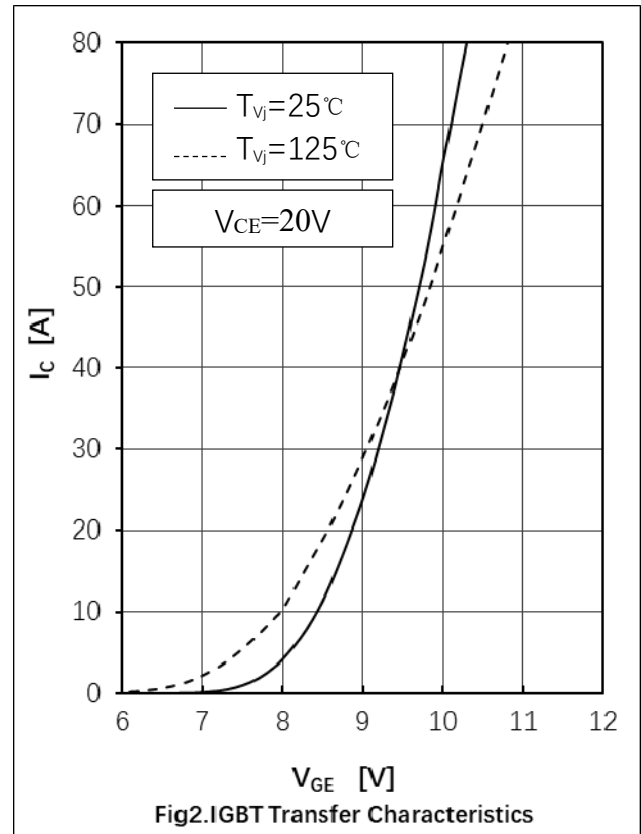
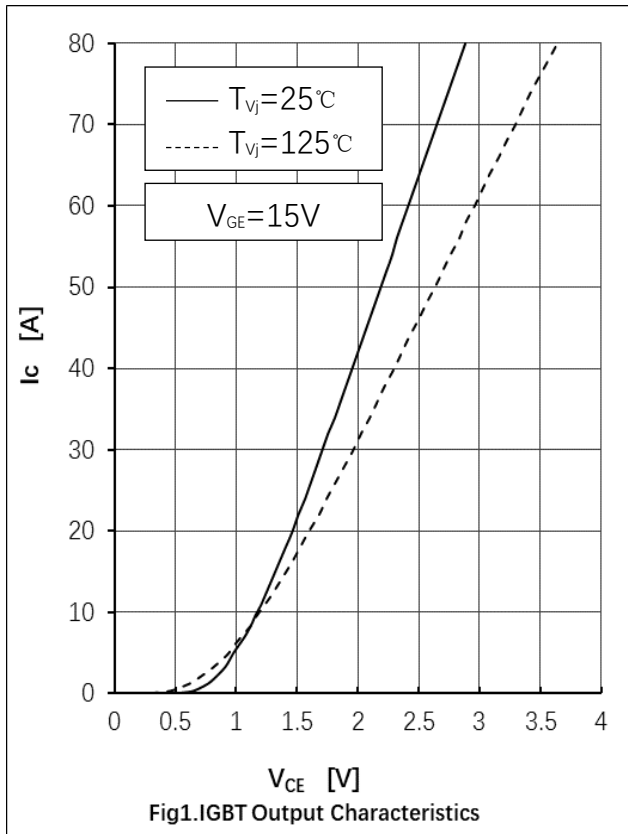


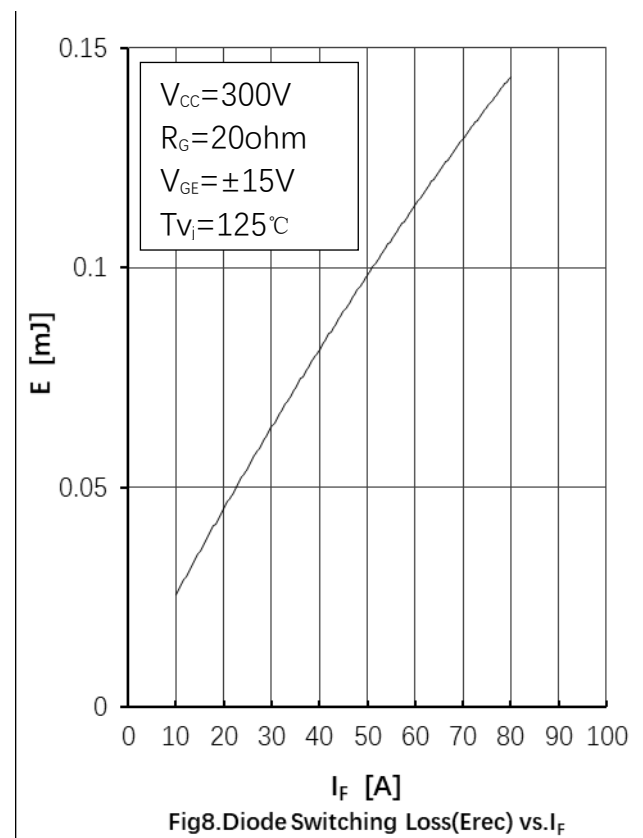
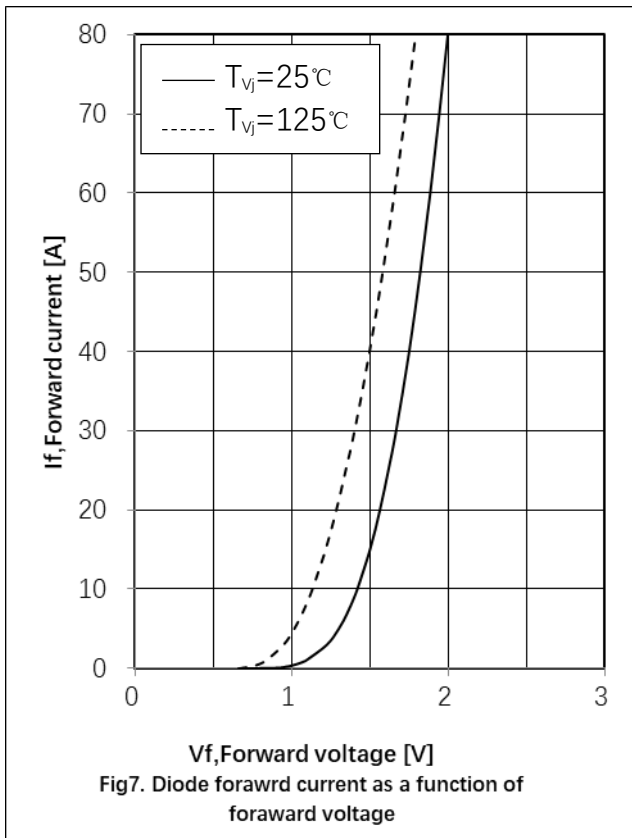
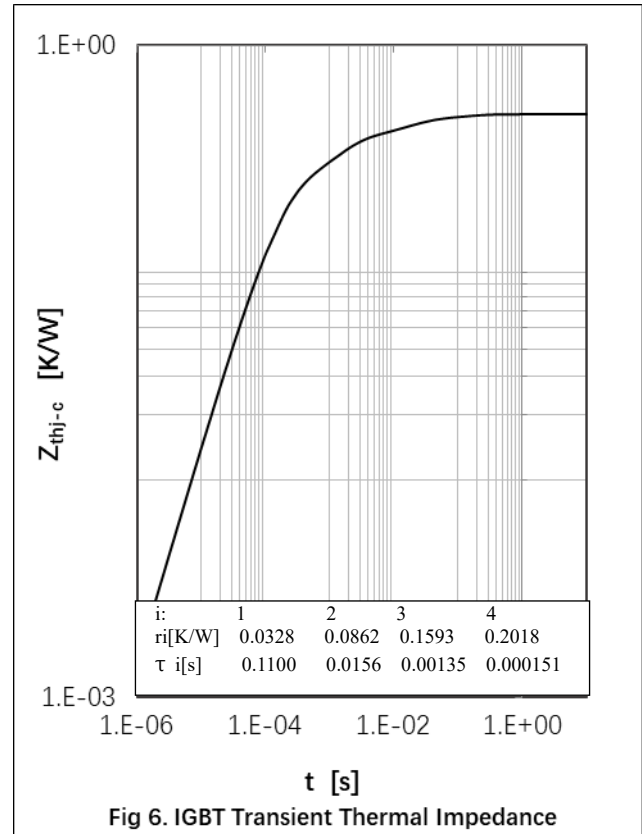
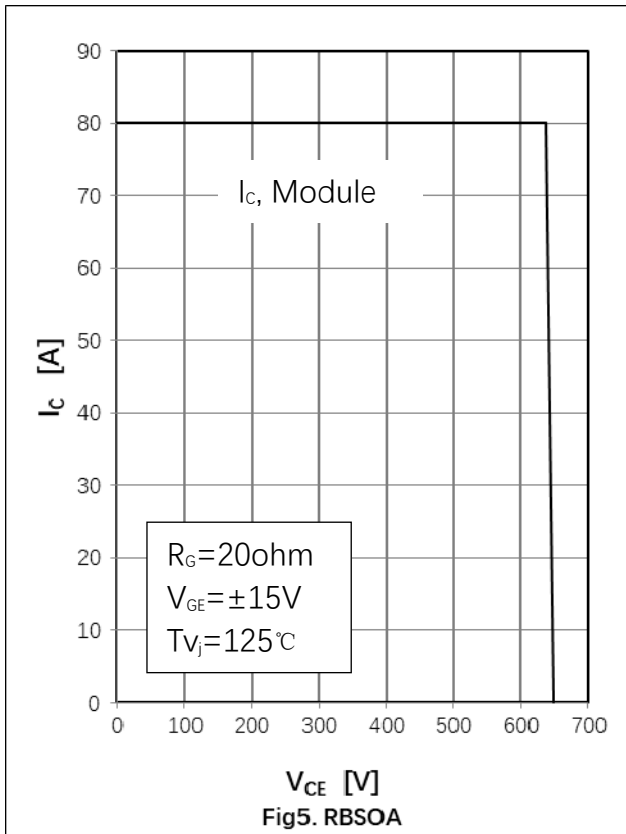
Electrical Characteristics of the DIODE

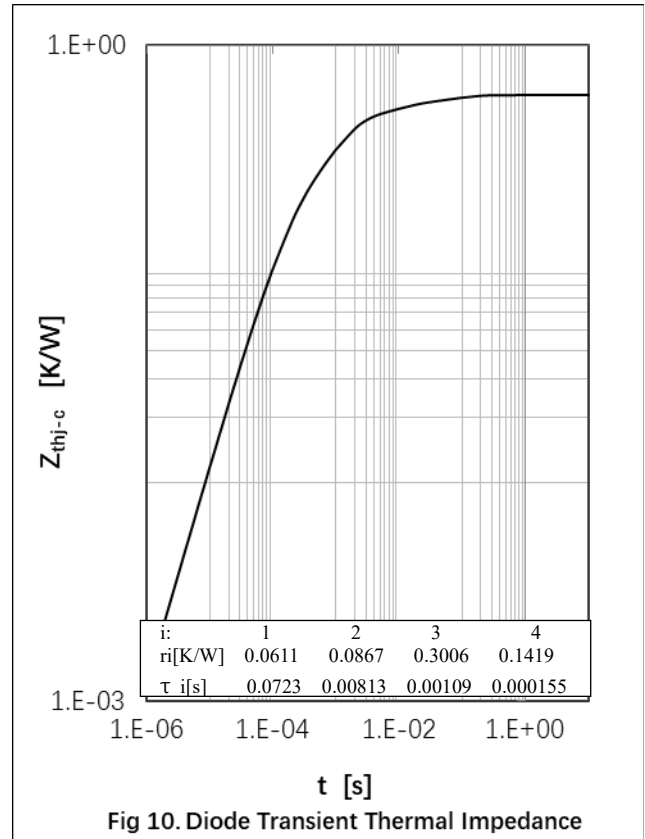
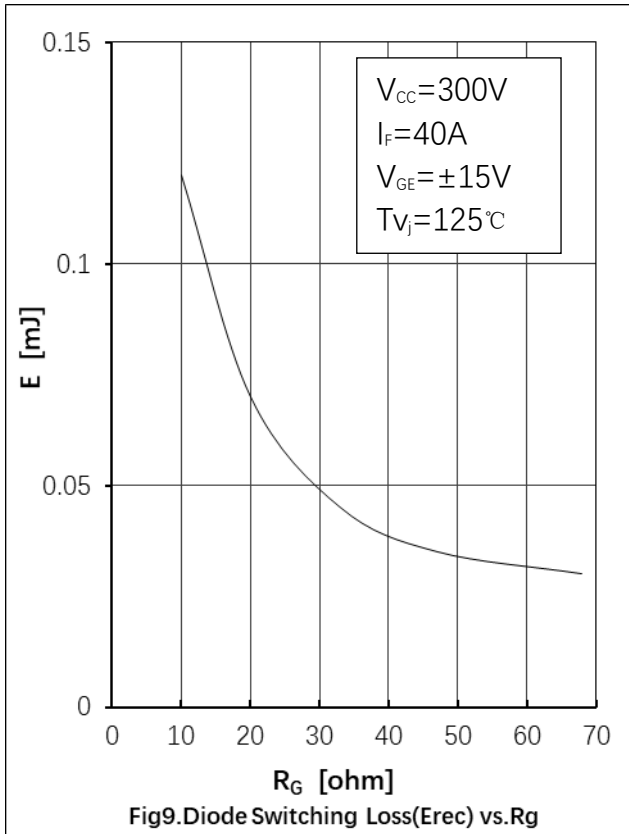
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic , at T_j= 25°C						
Reverse Recovery Current	I _{rr}	I _F =40A, V _R =300V di/dt= -750A/μs,	-	10	-	A
Reverse Recovery Charge	Q _{rr}		-	0.68	-	uC
Diode reverse recovery time	trr		-	128	-	ns
Reverse Recovery Energy	E _{rec}		-	0.09		mJ
Dynamic , at T_j= 125°C						
Reverse Recovery Current	I _{rr}	I _F =40A, V _R =300V di/dt= -750A/μs,	-	16	-	A
Reverse Recovery Charge	Q _{rr}		-	1.21	-	uC
Diode reverse recovery time	trr		-	155	-	ns
Reverse Recovery Energy	E _{rec}		-	0.20		mJ
Dynamic , at T_j= 150°C						
Reverse Recovery Current	I _{rr}	I _F =40A, V _R =300V di/dt= -750A/μs,	-	17	-	A
Reverse Recovery Charge	Q _{rr}		-	1.35	-	uC
Diode reverse recovery time	trr		-	158	-	ns
Reverse Recovery Energy	E _{rec}		-	0.25		mJ

Thermal Resistance

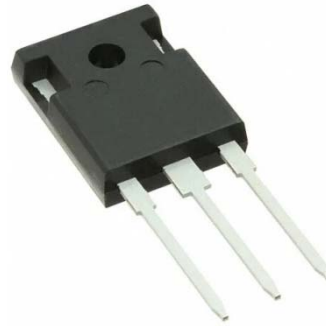
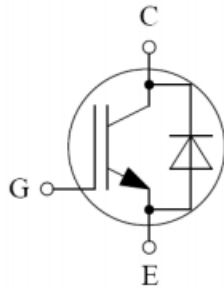
Parameter	Symbol	Max. Value	Unit
IGBT Thermal Resistance, Junction - Case	R _{th(j-c)}	0.49	K/W
Diode Thermal Resistance, Junction - Case	R _{th(j-c)}	0.59	K/W
Thermal Resistance, Junction - Ambient	R _{th(j-a)}	40	K/W





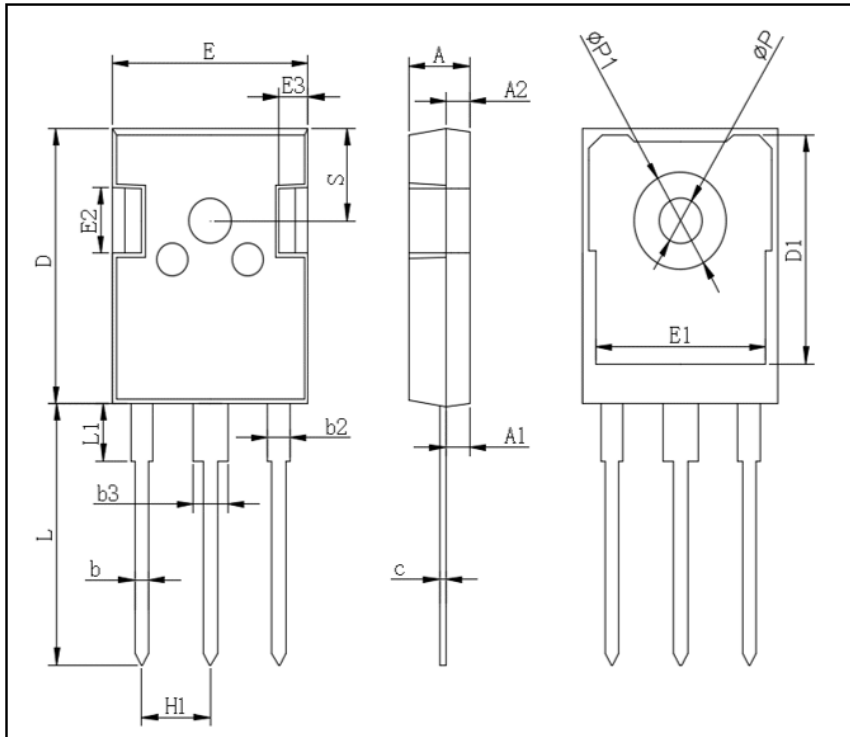


● Circuit Diagram



● Package Outline Information

CASE: TO 247



TO-247AB [□]		
Dim [□]	Min [□]	Max [□]
A [□]	4.80 [□]	5.20 [□]
A1 [□]	2.21 [□]	2.61 [□]
A2 [□]	1.85 [□]	2.15 [□]
b [□]	1.0 [□]	1.4 [□]
b2 [□]	1.91 [□]	2.21 [□]
C [□]	0.5 [□]	0.7 [□]
D [□]	20.70 [□]	21.30 [□]
D1 [□]	16.25 [□]	16.85 [□]
E [□]	15.50 [□]	16.10 [□]
E1 [□]	13.0 [□]	13.6 [□]
E2 [□]	4.80 [□]	5.20 [□]
E3 [□]	2.30 [□]	2.70 [□]
L [□]	19.62 [□]	20.22 [□]
L1 [□]	- [□]	4.30 [□]
ΦP [□]	3.40 [□]	3.80 [□]
$\Phi P1$ [□]	- [□]	7.30 [□]
S [□]	6.15TYP [□]	
H1 [□]	5.44TYP [□]	
b3 [□]	2.80 [□]	3.20 [□]